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1.0	PURPOSE/SCOPE
1.1	This document defines the design rules for the polyimide bridges.
1.2	This policy applies to all polyimide bridges manufactured by Applied Thin-Film Products.
2.0	BRIDGE DESIGN RULES
2.1	The minimum contact area (the area where the bridge attaches to the conductor) should be 1.0 mil (645 microns). <i>See Figure 1</i>
2.2	All bridges are plated to a minimum thickness of 160 microinches (4 microns).
2.3	The bridge length should be pulled back a minimum of 0.05 mil (1.27 microns) from the conductor edge. <i>See Figure 1</i>
2.4	Minimum bridge width is 1.0 mil (25.4 microns).
2.5	Unsupported areas of the bridge (the areas of the bridge that are not located on either the conductor or polyimide layer) should be kept to a minimum. <i>See Figure 1</i>
3.0	POLYIMIDE DESIGN RULES
3.1	The polyimide pad width should be three times (3X) as wide as the bridge width. <i>See Figure 1</i>
3.2	The length of the pad should be pulled back a minimum of 0.2 mil (5.08 microns) away from the area where the conductor contacts the bridge. Typical pullback is 50% of the gap (where applicable). <i>See figure 1</i>
3.3	The typical thickness of the polyimide is 160-200 microinches (4-5 microns)
3.4	The properties for the polyimide can be found in <i>Table A</i> .

THE DATA CONTAINED HEREIN CONSTITUTES PROPRIETARY INFORMATION OF APPLIED THIN-FILM PRODUCTS AND SHALL NOT BE USED,

	SIZE	CAGE CODE		DRAWING NU	IMBER	REV
APPLIED THIN-FILM PRODUCTS	A	04ZN)4ZMO 50031		50031	-
	SCALE				SHEET 2 OF	4

Polyimide Properties

		045
Tensile Strength	Мра	215
Young's Modulus	Gpa	2.5
Tensile Elongation	%	85
Glass Transition Temperature	°C	285
Thermal Decomposition Temperature	°C	525
Coefficient of Thermal Expansion	ppm/°C	55
Coating Stress (100 silicon)	MPa	33
Dielectric Constant 1MHz; 0%/50% RH		3.2/3.3
Dissipation Factor 1 MHz; 0%/50% RH		0.003/0.008
Dielectric Strength	V/µm	345
Moisture Absorption @ 50% RH	%	1.08
Density	g/cc	1.39
Refractive Index @ 633nm		1.69

Table A

THE DATA CONTAINED HEREIN CONSTITUTES PROPRIETARY INFORMATION OF APPLIED THIN-FILM PRODUCTS AND SHALL NOT BE USED,

	SIZE	CAGE CODE		DRAWING NU	IMBER	REV
APPLIED THIN-FILM PRODUCTS	A	04ZN	ИO		50031	-
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